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Robert  
Supp  
and

S/N 09/897,320

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh

Examiner: Gregory Thompson

Serial No.: 09/897,320

Group Art Unit: 2835

Filed: June 29, 2001

Docket: 884.462US1

Title: ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND  
METHODS OF MANUFACTURE

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SUPPLEMENTAL AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Further in response to the Office Action mailed on June 17, 2002, please amend the  
above-identified patent application as follows:

IN THE CLAIMS

Please substitute the claim set in the appendix entitled "Clean Version of Pending  
Claims" for the previously pending claim set. The substitute claim set reflects the cancellation of  
claim 16, the amendment of claims 1-3, 12, 13, and 17, and the addition of new claims 31-41.

Please cancel claim 16.

Please amend claims 1-3, 12, 13, and 17 as indicated below. The specific amendments to  
individual claims are detailed in the following marked-up set of claims.

1. (Twice Amended) An electronic assembly comprising:

a substrate having at least one hole therein;

a heat sink having at least one mounting pin; and

at least one heat-producing component attached to the substrate, wherein the heat sink is  
disposed over the at least one heat-producing component and the substrate, wherein the heat-  
producing component is sandwiched between the substrate and the heat sink, wherein a thermal  
interface material is disposed between the heat sink and the heat-producing component to couple  
[bond] the heat sink to the heat-producing component, and wherein the at least one mounting pin  
of the heat sink is soldered into the at least one hole of [to] the substrate.